

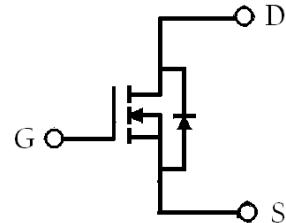
N -Channel Enhancement Mode Power MOSFET

Equivalent Circuit

Features:

- Low Gate Charge
- Simple Drive Requirement
- Pb-free lead plating and halogen-free package

KWU300N2013S

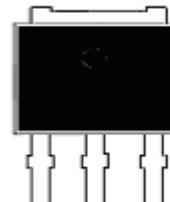


G : Gate D : Drain

S : Source

Outline

TO-251S



G D S

| | |
|-------------------------------|--------------------|
| BVDSS | 200V |
| ID@VGS=10V, Tc=25°C | 8.3A |
| RDS(ON)@VGS=10V, Id=3A | 294mΩ (typ) |

Ordering Information

| Device | Package | Shipping |
|--------------|--|---------------------------|
| KWU300N2013S | TO-251S (RoHS compliant and halogen-free package) | 80 pcs/tube, 50 tubes/box |



Absolute Maximum Ratings (TC=25°C, unless otherwise noted)

| Parameter | Symbol | Limits | Unit |
|---|-----------------------------------|-----------------|------|
| Drain-Source Voltage | V _{DS} | 200 | V |
| Gate-Source Voltage | V _{GS} | ±30 | |
| Continuous Drain Current @ T _c =25°C, V _{GS} =10V | I _D | 8.3 | A |
| Continuous Drain Current @ T _c =100°C, V _{GS} =10V | | 5.3 | |
| Pulsed Drain Current *1 | | I _{DM} | |
| Avalanche Current | I _{AS} | 4 | mJ |
| Avalanche Energy @ L=10mH, I _{AS} =4A, V _{DD} =50V, V _{GS} =10V *3 | E _{AS} | 80 | |
| Repetitive Avalanche Energy @ L=0.05mH *2 | E _{AR} | 5 | |
| Total Power Dissipation @T _c =25°C | P _D | 50 | W |
| Total Power Dissipation @T _c =100°C | | 20 | |
| Operating Junction and Storage Temperature Range | T _j , T _{stg} | -55~+150 | °C |

Note : *1. Pulse width limited by maximum junction temperature

*2. Duty cycle ≤ 1%

*3. 100% tested by conditions of L=10mH, I_{AS}=3A, V_{GS}=10V, V_{DD}=50V

Thermal Data

| Parameter | Symbol | Value | Unit |
|--|------------------|-------|------|
| Thermal Resistance, Junction-to-case, max | R _{θJC} | 2.5 | °C/W |
| Thermal Resistance, Junction-to-ambient, max | R _{θJA} | 110 | |

Characteristics (T_c=25°C, unless otherwise specified)

| Symbol | Min. | Typ. | Max. | Unit | Test Conditions |
|-------------------------------------|------|------|------|------|--|
| Static | | | | | |
| BV _{DSS} | 200 | - | - | V | V _{GS} =0V, I _D =250μA |
| ΔBV _{DSS} /ΔT _j | - | 0.2 | - | V/°C | Reference to 25°C, I _D =250μA |
| V _{GS(th)} | 2 | - | 4 | V | V _{DS} =V _{GS} , I _D =250μA |
| G _{FS} *1 | - | 3.2 | - | S | V _{DS} =15V, I _D =2A |
| I _{GSS} | - | - | ±100 | nA | V _{GS} =±30V, V _{DS} =0V |
| I _{DSS} | - | - | 1 | μA | V _{DS} =160V, V _{GS} =0V |
| | - | - | 25 | | V _{DS} =160V, V _{GS} =0V, T _j =125°C |
| R _{D(S(ON))} *1 | - | 294 | 360 | mΩ | V _{GS} =10V, I _D =3A |
| Dynamic | | | | | |
| Q _g *1, 2 | - | 10.2 | - | nC | I _D =3A, V _{DS} =160V, V _{GS} =10V |
| Q _{gs} *1, 2 | - | 2.2 | - | | |
| Q _{gd} *1, 2 | - | 3.8 | - | | |
| t _{d(ON)} *1, 2 | - | 8.8 | - | ns | V _{DS} =100V, I _D =3A, V _{GS} =10V, R _G =25Ω |
| t _r *1, 2 | - | 17 | - | | |
| t _{d(OFF)} *1, 2 | - | 21.2 | - | | |
| t _f *1, 2 | - | 20.4 | - | | |

| | | | | | |
|---------------------------|---|------|-----|----|---|
| C _{iss} | - | 373 | - | pF | V _{GS} =0V, V _{DS} =25V, f=1MHz |
| C _{oss} | - | 46 | - | | |
| C _{rss} | - | 20 | - | | |
| Source-Drain Diode | | | | | |
| I _s *1 | - | - | 8.3 | A | |
| I _{SM} *3 | - | - | 18 | | |
| V _{SD} *1 | - | 0.78 | 1.2 | V | I _s =2A, V _{GS} =0V |
| t _{rr} | - | 54 | - | ns | I _F =3A, dI _F /dt=100A/μs |
| Q _{rr} | - | 105 | - | nC | |

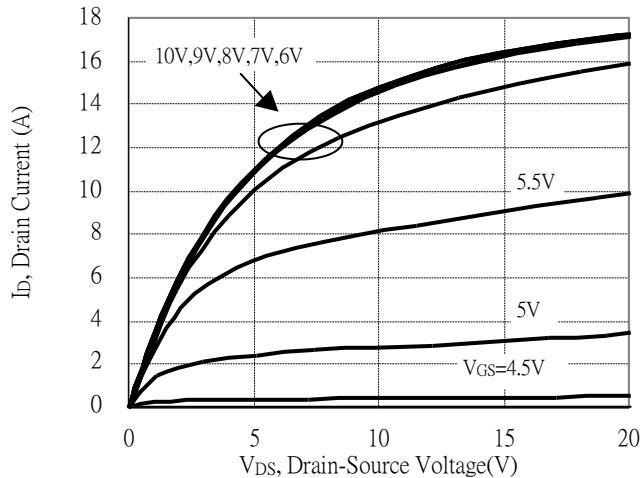
Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

*2.Independent of operating temperature

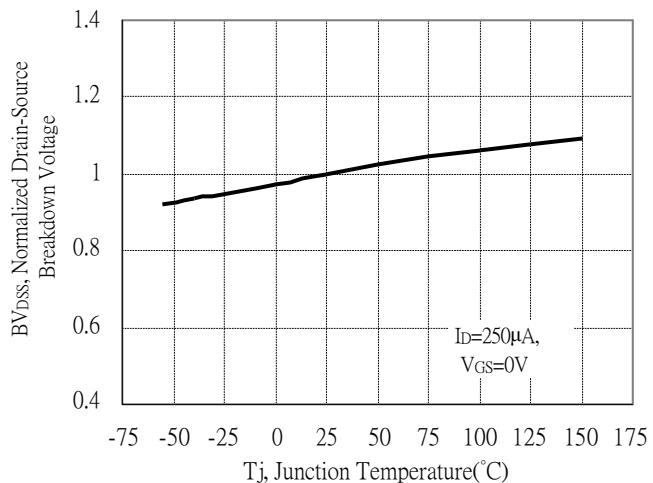
*3.Pulse width limited by maximum junction temperature.

Typical Characteristics

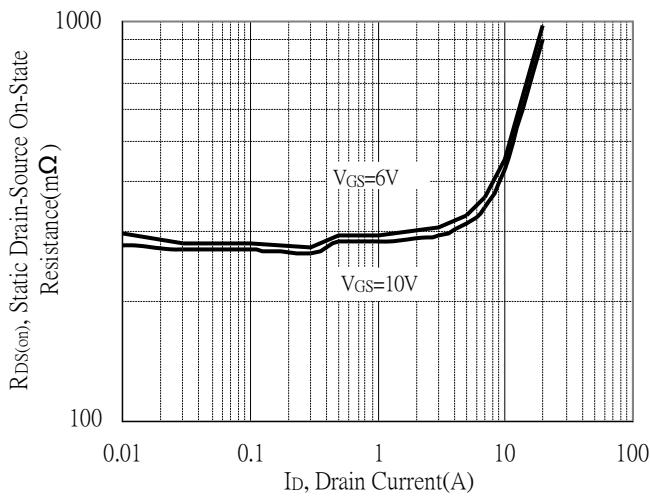
Typical Output Characteristics



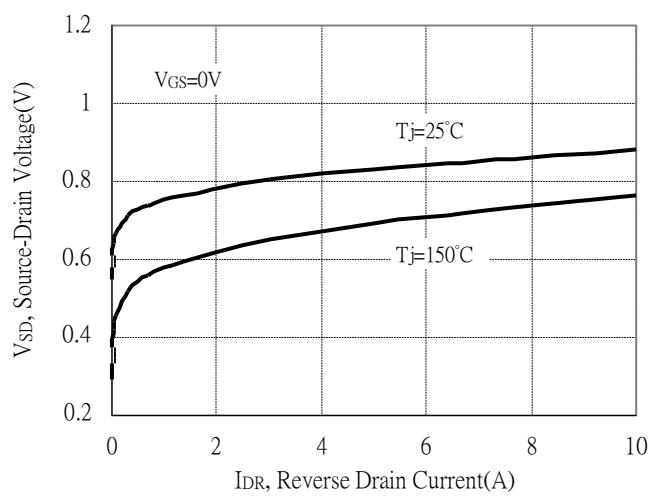
Breakdown Voltage vs Ambient Temperature



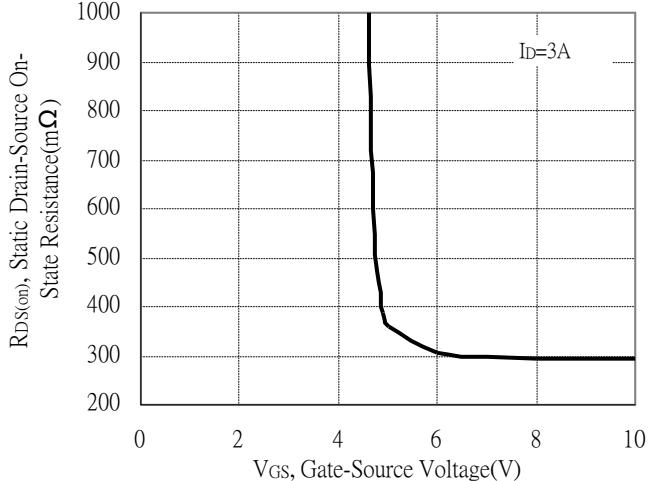
Static Drain-Source On-State resistance vs Drain Current



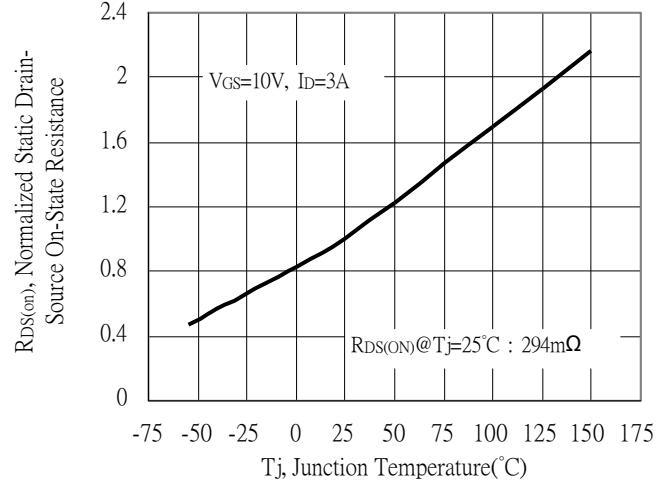
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

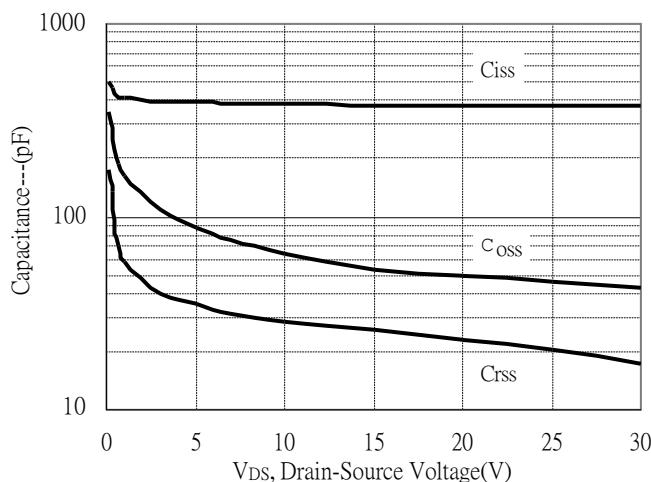


Drain-Source On-State Resistance vs Junction Temperature

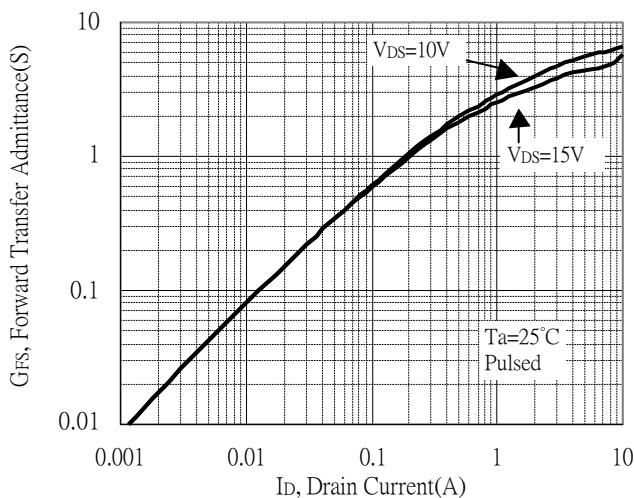


Typical Characteristics(Cont.)

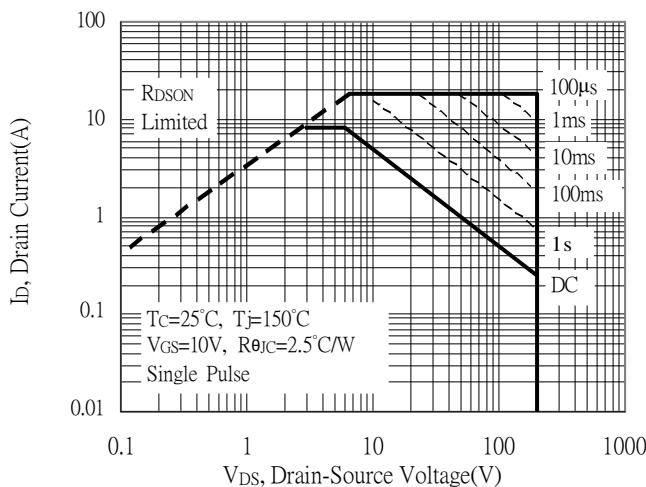
Capacitance vs Drain-to-Source Voltage



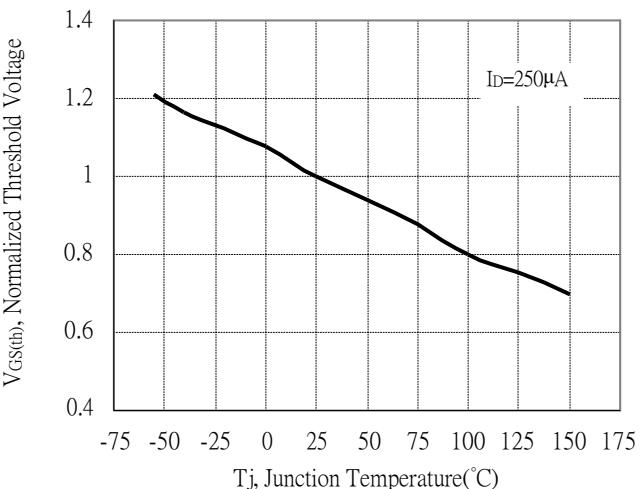
Forward Transfer Admittance vs Drain Current



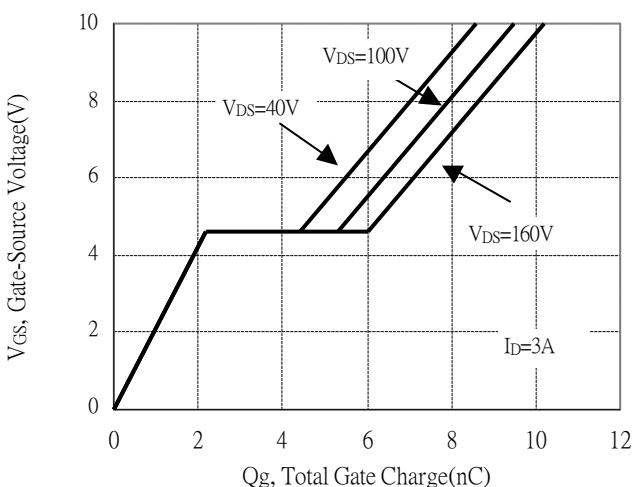
Maximum Safe Operating Area



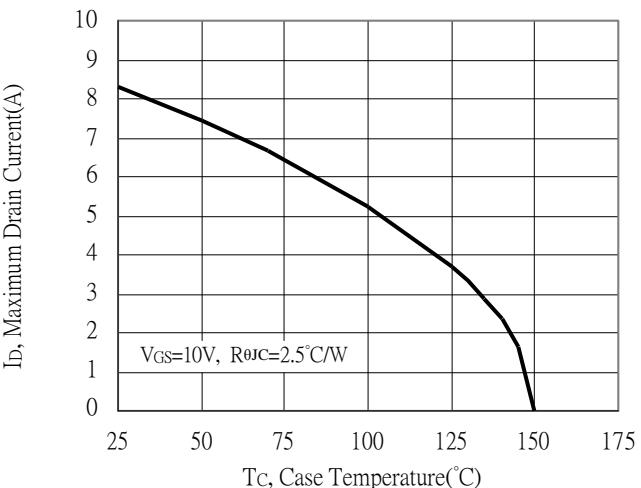
Threshold Voltage vs Junction Temperature



Gate Charge Characteristics

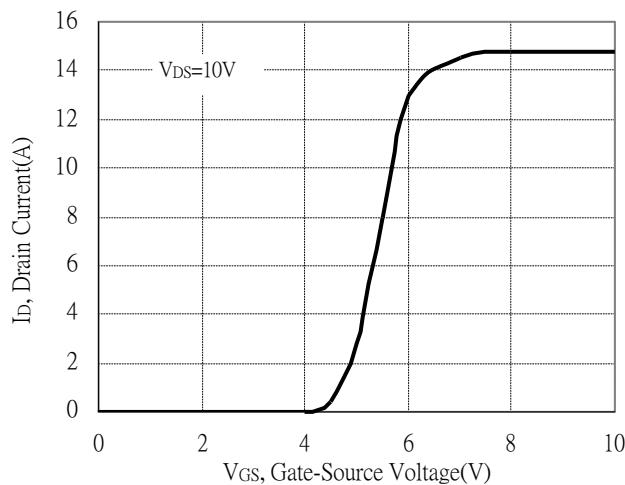


Maximum Drain Current vs Case Temperature

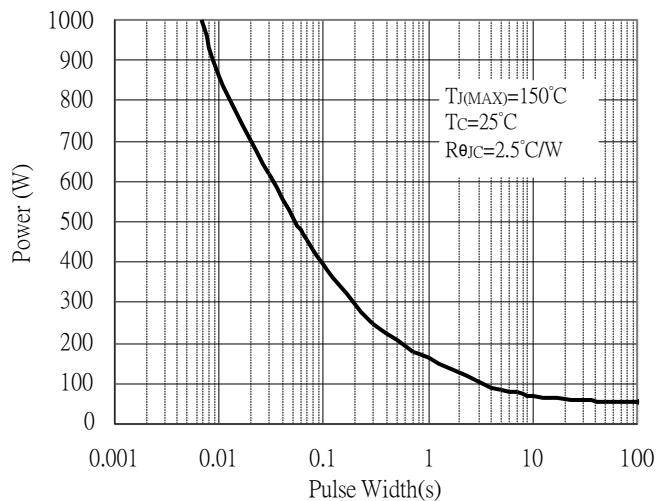


Typical Characteristics(Cont.)

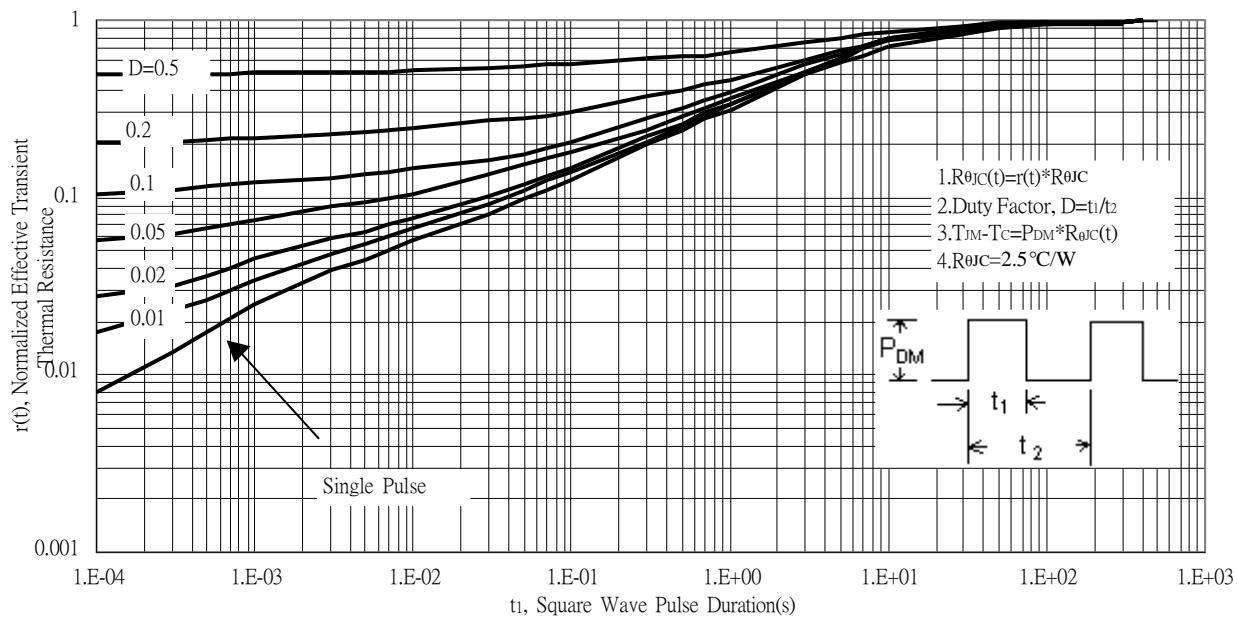
Typical Transfer Characteristics



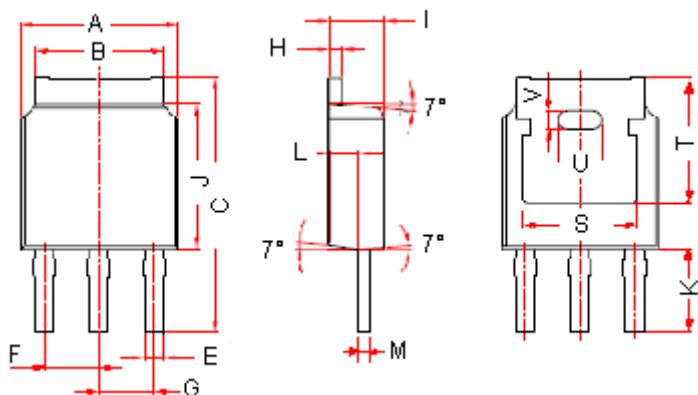
Single Pulse Power Rating, Junction to Case



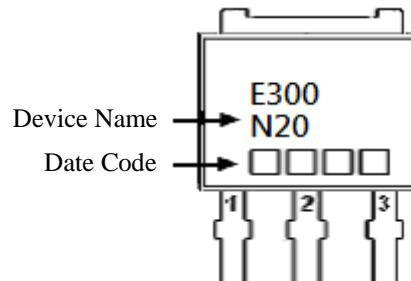
Transient Thermal Response Curves



TO-251S Dimension



Marking :



3-Lead TO-251S Plastic Package
 Package Code: I3S

Style : Pin 1. Gate 2. Drain 3. Source

| DIM | Inches | | Millimeters | | DIM | Inches | | Millimeters | |
|-----|--------|--------|-------------|-------|-----|--------|--------|-------------|------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| A | 0.2559 | 0.2638 | 6.50 | 6.70 | J | 0.2362 | 0.2441 | 6.00 | 6.20 |
| B | 0.2020 | 0.2126 | 5.13 | 5.46 | K | 0.1299 | 0.1457 | 3.30 | 3.70 |
| C | 0.4094 | 0.4331 | 10.40 | 11.00 | L | 0.0358 | 0.0437 | 0.91 | 1.11 |
| E | 0.0280 | 0.0319 | 0.71 | 0.81 | M | 0.0181 | 0.0220 | 0.46 | 0.56 |
| F | 0.0858 | 0.0941 | 2.18 | 2.39 | S | 0.1902 | REF | 4.83 | REF |
| G | 0.0858 | 0.0941 | 2.18 | 2.39 | T | 0.2106 | REF | 5.35 | REF |
| H | 0.0181 | 0.0220 | 0.46 | 0.56 | U | 0.0701 | REF | 1.78 | REF |
| I | 0.0902 | 0.0937 | 2.29 | 2.38 | V | 0.0299 | REF | 0.76 | REF |